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RX240160A-GHW

SPECIFICATION

CUSTOMER:

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

ISSUED DATE:



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1. Revision History

DATE	VERSION	REVISED PAGE NO.	Note
2012/11/30	1		First issue



2. General Specification

The Features of the Module is description as follow:

■ Module dimension: 93.0 x 64.2 x 9.8(MAX) mm3

View area: 78.5 x 47.5 mm2

Active area: 69.58 x 43.98 mm2

■ Number of Characters: 240 x 160 dots

■ Dot size: 0.27 x 0.255 mm2

■ Dot pitch: 0.29 x 0.275 mm2

■ LCD type: STN Positive, Gray Transflective

■ Duty: 1/160DUTY,1/12BIAS

■ View direction: 6 o'clock

■ Backlight Type: LED, White



3. Module Coding System

R	Х	240160	Α	-	G	Н	W
1	2	3	4	-	5	6	7

Item		Description	on
1	R: Raystar C	ptronics Inc.	
2	Display Type:	COG	
3	Display Font :	240 x 160 dots	
4	Serials code		
		P: TN Positive, Gray	A The second of
		N: TN Negative,	
		G: STN Positive, Gray	
5	LCD	Y: STN Positive, Yellow Gr	een
		B: STN Negative, Blue	
		F: FSTN Positive	
		T: FSTN Negative	
		A: Reflective, N.T, 6:00	K: Transflective, W.T,12:00
	Polarizer	D: Reflective, N.T, 12:00	1: Transflective, U.T,6:00
	Type,	G: Reflective, W. T, 6:00	4: Transflective, U.T.12:00
	Tamporatura	J: Reflective, W. T, 12:00	C: Transmissive, N.T,6:00
6	Temperature range,	0: Reflective, U. T, 6:00	F: Transmissive, N.T,12:00
	rango,	3: Reflective, U. T, 12:00	I: Transmissive, W. T, 6:00
	View	B: Transflective, N.T,6:00	L: Transmissive, W.T,12:00
	direction	E: Transflective, N.T.12:00	2: Transmissive, U. T, 6:00
		H: Transflective, W.T,6:00	5: Transmissive, U.T,12:00
		N : Without backlight	Y: LED, Yellow Green
		P: EL, Blue green	A: LED, Amber
7	Backlight	T: EL, Green	W: LED, White
		D: EL, White	O: LED, Orange
		F: CCFL, White	G: LED, Green

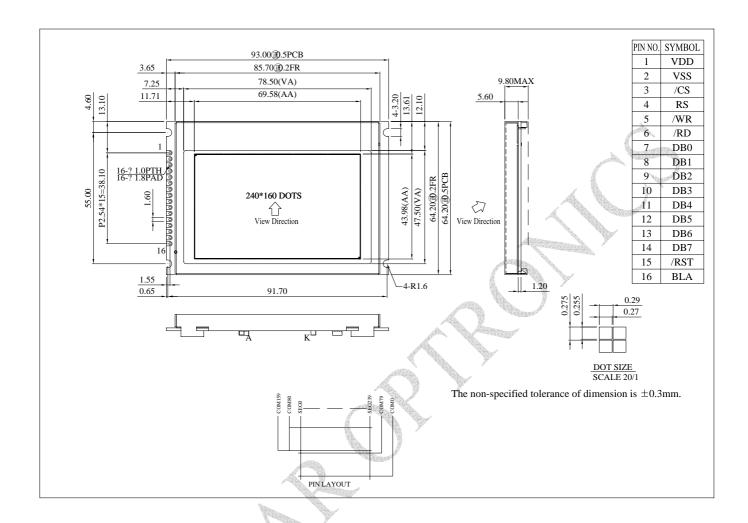


4. Interface Pin Function

Pin No.	Symbol	Level	Description
1	VDD		Power supply (+3.3V)
2	VSS		Power supply
3	/CS	L	Chip enable active " L "
4	RS	H/L	H: Instruction, L: Data
5	/WR	L	Write enable input,active Low
6	/RD	L	Read enable input,active Low
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line
15	/RST		Reset input pin
			/RST =Low, initialization is executed /RST =High, Normal
16	BLA	Power	Backlight Positive Power Supply



5. Outline Dimension





6.Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T _{OP}	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T _{ST}	-30	_	+80	$^{\circ}$ C
Supply voltage for Logic	$V_{DD-}V_{SS}$	-0.5	_	4.0	V
Output voltage	Vo	-0.5		V _{DD} +0.5	V

7. Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V_{DD} - V_{SS}	_ <	3.0	3.3	3.6	V
		Ta=-20°℃				V
Supply Voltage For LCD	V_{O} - V_{SS}	Ta=25°C		14.5	_	V
		Ta=70°C		ĺ		V
Input High Volt.	V _{jH}	_	$0.7 V_{DD}$		V_{DD}	V
Input Low Volt.	V _{IL}		V _{SS}	_	$0.3V_{DD}$	V
Output High Volt.	V _{OH}	_	V _{DD} -0.4	_	_	V
Output Low Volt.	V _{OL}	_	V_{SS}	_	0.4	V
Supply Current(No include LED Backlight)	I _{DD}	V _{DD} =3.3V	_	4.8	_	mA

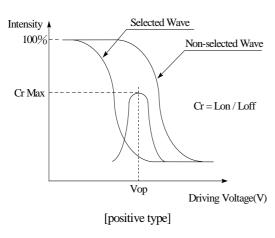
Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance.

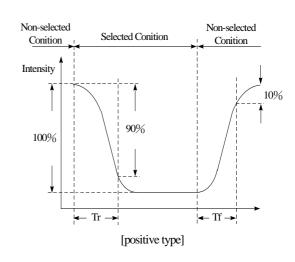
8.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V)θ	CR≧2	20	_	40	deg
View / tilgie	(Η)φ	CR≧2	-30	_	30	deg
Contrast Ratio	CR	_	_	3	_	_
Response Time	T rise	_	_	200	300	ms
copoco /iiiio	T fall	_	_	200	300	ms

Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)



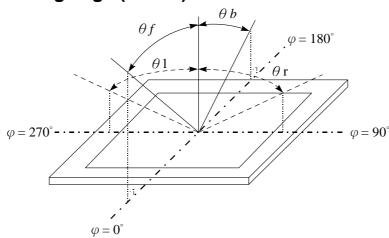


Conditions:

Operating Voltage : Vop Viewing Angle(θ , ϕ) : 0° , 0°

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle(CR≥2)





9. Timing Characteristics

PLEASE TO CONSULT ST7529 SPEC





10. Backlight Information

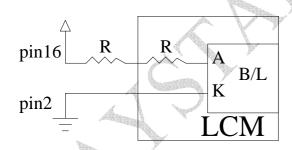
Specification

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	76.8	96.0	120	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	٧	
Reverse Voltage	VR	_	_	5	V	-
Luminous Intensity (Without LCD)	IV	640.0	800.0	_	CD/M ²	ILED=96mA
LED Life Time	_	_	50K	_	Hr.	ILED≦96mA
Color	White			A		

Note: The LED of B/L is drive by current only; driving voltage is only for reference To make driving current in safety area (waste current between minimum and maximum).

Note1:50K hours is only an estimate for reference.

Drive from pin16,pin2





11. Reliability

Content of Reliability Test (wide temperature, -20°c~70°C)

Environmental Test							
Test Item	Content of Test	Condition	Note				
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 200hrs	2				
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30℃ 200hrs	1,2				
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs	-				
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 200hrs	1				
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60℃,90%RH 96hrs	1,2				
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20℃/70℃ 10 cycles	-				
Vibration test	Endurance test applying the vibration during transportation and using.	fixed amplitude: 15mm Vibration. Frequency: 10~55Hz. One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3				
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS= 1.5kΩ CS=100pF 1 time					

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



12. Inspection specification

NO	Item	Criterion				AQL
01	Electrical Testing	 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. 				0.65
02	Black or white spots on LCD (display only)	 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 				2.5
03	LCD black spots, white spots, contaminatio	3.1 Round type : As following drawing Φ=(x+y)/2				2.5
	n (non-display)	3.2 Line type : ((As follow Length L≦3.0 L≦2.5	wing drawing) Width W≦0.02 0.02 <w≦0.03 0.03<w≦0.05="" 0.05<w<="" td=""><td>Acceptable Q TY Accept no dense 2 As round type</td><td>2.5</td></w≦0.03>	Acceptable Q TY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.		Size Φ $ Φ \le 0.20 $ $ 0.20 < Φ \le 0.50 $ $ 0.50 < Φ \le 1.00 $ $ 1.00 < Φ $ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3	2.5



NO	Item	Criterion			AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination			
		Symbols Define: x: Chip length y k: Seal width t: L: Electrode pad lengt 6.1 General glass chip 6.1.1 Chip on panel su	: Chip width z: C Glass thickness a: h:	hip thickness LCD side length	
06	Chipped glass	z: Chip thickness $Z \le 1/2t$ $1/2t < z \le 2t$ $\odot \text{ If there are 2 or monomode}$ $6.1.2 \text{ Corner crack:}$	y: Chip width Not over viewing area Not exceed 1/3k re chips, x is total leng	x: Chip length x≤1/8a x≤1/8a gth of each chip.	2.5
		z: Chip thickness $Z \le 1/2t$ $1/2t < z \le 2t$ \odot If there are 2 or more	y: Chip width Not over viewing area Not exceed 1/3k re chips, x is the total	x: Chip length x≤1/8a x≤1/8a length of each chip.	



NO	Item	Criterion	AQL
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:	
		$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	
06	Glass crack	y Z Z X Z Z X X Z Z X X X X X X X X X X	2.5
		y: Chip width x: Chip length z: Chip thickness $y \le L$ $x \le 1/8a$ $0 < z \le t$ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width x: length $y \le 1/3L$ $x \le a$	



NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB · COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB 	2.5 2.5 0.65 2.5 0.65 2.5 2.5 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB.11.2 No cold solder joints, missing solder connections, oxidation or icicle.11.3 No residue or solder balls on PCB.	2.5 2.5 2.5 0.65
		11.4 No short circuits in components on PCB.	



NO	Item	Criterion	AQL
12	General appearance	 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet. 	2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65 0.65

13. Precautions in use of LCD Modules

- 1. Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- 2. Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- 3. Don't disassemble the LCM.
- 4. Don't operate it above the absolute maximum rating.
- 5. Don't drop, bend or twist LCM.
- 6. Soldering: only to the I/O terminals.
- 7. Storage: please storage in anti-static electricity container and clean environment.
- 8. Raystar have the right to change the passive components (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- 9. Raystar have the right to change the PCB Rev.



14. Material List of Components for RoHs

1. RAYSTAR Optronics Co., Ltd. hereby declares that all of or part of products, including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

2. Process for RoHS requirement:

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow: 250°C, 30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°€;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.

15. Recommendable storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module



Page: 1

LCM Sample Estimate Feedback Sheet					
Module Number :					
1 · Panel Specification :					
1. Panel Type:	□ Pass	□ NG ,			
2. View Direction:	□ Pass	□ NG ,			
3. Numbers of Dots:	□ Pass	□ NG ,			
4. View Area:	□ Pass	□ NG ,			
5. Active Area:	□ Pass	□ NG ,			
6.Operating	□ Pass	□ NG ,			
Temperature :					
7.Storage Temperature:	□ Pass	□ NG ,			
8.Others:					
2 · Mechanical Specification	<u>on</u> :				
1. PCB Size:	□ Pass	□ NG ,			
2.Frame Size :	□ Pass	□ NG ,			
3.Materal of Frame:	□ Pass	□ NG ,			
4.Connector Position:	□ Pass	□ NG ,			
5.Fix Hole Position:	□ Pass	□ NG ,			
6.Backlight Position:	□ Pass	□ NG ,			
7. Thickness of PCB:	□ Pass	□ NG ,			
8. Height of Frame to	□ Pass	□ NG ,			
PCB:					
9.Height of Module:	□ Pass	□ NG ,			
10.Others:	□ Pass	□ NG ,			
3 · Relative Hole Size :					
1.Pitch of Connector :	□ Pass	□ NG ,			
2.Hole size of	□ Pass	□ NG ,			
Connector:	JP.				
3.Mounting Hole size	□ Pass	□ NG ,			
4.Mounting Hole Type:	□ Pass	□ NG ,			
5.Others:	□ Pass	□ NG ,			
4 · Backlight Specification :					
1.B/L Type:	□ Pass	□ NG ,			
2.B/L Color:	□ Pass	□ NG ,			
3.B/L Driving Voltage (Reference for LED Type) : □ Pass □ NG ,					
4.B/L Driving Current:	□ Pass	□ NG ,			
5.Brightness of B/L:	□ Pass	□ NG ,			
6.B/L Solder Method:	□ Pass	□ NG ,			
7.Others:	□ Pass	□ NG ,			

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Page: 2

Module Number :					
5 · Electronic Characteristics of Module :					
1.Input Voltage :	□ Pass	□ NG ,			
2.Supply Current : □ Pas		□ NG ,			
3.Driving Voltage for LCD:	□ Pass	□ NG ,			
4.Contrast for LCD:	□ Pass	□ NG ,			
5.B/L Driving Method:	□ Pass	□ NG ,			
6.Negative Voltage	□ Pass	□ NG ,			
Output:					
7.Interface Function:	□ Pass	□ NG ,			
8.LCD Uniformity:	□ Pass	□ NG ,			
9.ESD test:	□ Pass	□ NG ,			
10.Others:	□ Pass	□ NG ,			
6 ⋅ <u>Summary</u> :					
6 · Summary:					
Sales signature: Customer Signature	•	 			
.					